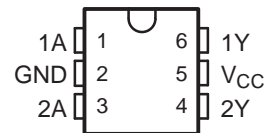


DUAL INVERTER BUFFER/DRIVER WITH OPEN-DRAIN OUTPUTS

FEATURES

- Qualified for Automotive Applications
- Supports 5-V V_{CC} Operation
- Max t_{pd} of 3.4 ns at 3.3 V
- Low Power Consumption, 10- μ A Max I_{CC}
- ± 24 -mA Output Drive at 3.3 V
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- Typical V_{OHV} (Output V_{OH} Undershoot) > 2 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- Inputs and Open-Drain Outputs Accept Voltages up to 5.5 V
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DBV OR DCK PACKAGE
(TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

This dual inverter buffer/driver is designed for 1.65-V to 5.5-V V_{CC} operation.

The output of the SN74LVC2G06-Q1 device is open drain and can be connected to other open-drain outputs to implement active-low wired-OR or active-high wired-AND functions. The maximum sink current is 32 mA.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION⁽¹⁾

| T_A | PACKAGE ⁽²⁾ | | ORDERABLE PART NUMBER | TOP-SIDE MARKING ⁽³⁾ |
|----------------|------------------------|---------------|-----------------------|---------------------------------|
| -40°C to 125°C | SOT (SOT-23) – DBV | Tape and reel | SN74LVC2G06QDBVRQ1 | C06_ |
| | SOT (SC-70) – DCK | Tape and reel | SN74LVC2G06QDCKRQ1 | CT_ |

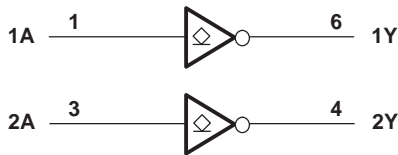
- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
- (2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.
- (3) DBV/DCK: The actual top-side marking has one additional character that designates the wafer fab/assembly site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).

FUNCTION TABLE (EACH INVERTER)

| INPUT A | OUTPUT Y |
|------------|-------------|
| H | L |
| L | H |



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

LOGIC DIAGRAM (POSITIVE LOGIC)**Absolute Maximum Ratings⁽¹⁾**

over operating free-air temperature range (unless otherwise noted)

| | | MIN | MAX | UNIT |
|---------------|---|-------------|------|------|
| V_{CC} | Supply voltage range | -0.5 | 6.5 | V |
| V_I | Input voltage range ⁽²⁾ | -0.5 | 6.5 | V |
| V_O | Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾ | -0.5 | 6.5 | V |
| V_O | Voltage range applied to any output in the high or low state ⁽²⁾⁽³⁾ | -0.5 | 6.5 | V |
| I_{IK} | Input clamp current | | -50 | mA |
| | | $V_I < 0$ | | |
| I_{OK} | Output clamp current | | -50 | mA |
| | | $V_O < 0$ | | |
| I_O | Continuous output current | | ±50 | mA |
| | Continuous current through V_{CC} or GND | | ±100 | mA |
| θ_{JA} | Package thermal impedance ⁽⁴⁾ | DBV package | 165 | °C/W |
| | | DCK package | 259 | |
| T_{stg} | Storage temperature range | -65 | 150 | °C |

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of V_{CC} is provided in the recommended operating conditions table.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions⁽¹⁾

| | | | MIN | MAX | UNIT |
|-----------------|------------------------------------|---|------------------------|-----|------|
| V _{CC} | Supply voltage | Operating | 1.65 | 5.5 | V |
| | | Data retention only | 1.5 | | |
| V _{IH} | High-level input voltage | V _{CC} = 1.65 V to 1.95 V | 0.65 × V _{CC} | | V |
| | | V _{CC} = 2.3 V to 2.7 V | 1.7 | | |
| | | V _{CC} = 3 V to 3.6 V | 2 | | |
| | | V _{CC} = 4.5 V to 5.5 V | 0.7 × V _{CC} | | |
| V _{IL} | Low-level input voltage | V _{CC} = 1.65 V to 1.95 V | 0.35 × V _{CC} | | V |
| | | V _{CC} = 2.3 V to 2.7 V | 0.7 | | |
| | | V _{CC} = 3 V to 3.6 V | 0.8 | | |
| | | V _{CC} = 4.5 V to 5.5 V | 0.3 × V _{CC} | | |
| V _I | Input voltage | | 0 | 5.5 | V |
| V _O | Output voltage | | 0 | 5.5 | V |
| I _{OL} | Low-level output current | V _{CC} = 1.65 V | 4 | | mA |
| | | V _{CC} = 2.3 V | 8 | | |
| | | V _{CC} = 3 V | 16 | | |
| | | | 24 | | |
| | | V _{CC} = 4.5 V | 32 | | |
| Δt/Δv | Input transition rise or fall rate | V _{CC} = 1.8 V ± 0.15 V, 2.5 V ± 0.2 V | 20 | | ns/V |
| | | V _{CC} = 3.3 V ± 0.3 V | 10 | | |
| | | V _{CC} = 5 V ± 0.5 V | 5 | | |
| T _A | Operating free-air temperature | | -40 | 125 | °C |

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | | V _{CC} | MIN | TYP ⁽¹⁾ | MAX | UNIT | |
|------------------------|--|--------------------------------|-----------------|-------|--------------------|------|------|------|
| V _{OL} | I _{OL} = 100 μA | | 1.65 V to 5.5 V | | | 0.1 | V | |
| | I _{OL} = 4 mA | | 1.65 V | | | 0.45 | | |
| | I _{OL} = 8 mA | | 2.3 V | | | 0.3 | | |
| | I _{OL} = 16 mA | T _A = -40°C to 85°C | | 3 V | | | | 0.4 |
| | | T _A = 125°C | | | | | | 0.45 |
| | I _{OL} = 24 mA | T _A = -40°C to 85°C | | 3 V | | | | 0.55 |
| | | T _A = 125°C | | | | | | 0.65 |
| | I _{OL} = 32 mA | T _A = -40°C to 85°C | | 4.5 V | | | | 0.55 |
| T _A = 125°C | | | | | 0.65 | | | |
| I _I | A inputs | V _I = 5.5 V or GND | 0 to 5.5 V | | | ±5 | μA | |
| I _{off} | V _I or V _O = 5.5 V | | 0 | | | ±10 | μA | |
| I _{CC} | V _I = 5.5 V or GND, I _O = 0 | | 1.65 V to 5.5 V | | | 10 | μA | |
| ΔI _{CC} | One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND | | 3 V to 5.5 V | | | 500 | μA | |
| C _i | V _I = V _{CC} or GND | | 3.3 V | | | 3.5 | pF | |

(1) All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 1](#))

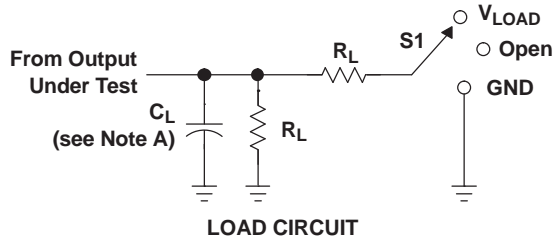
| PARAMETER | FROM (INPUT) | TO (OUTPUT) | $V_{CC} = 1.8\text{ V} \pm 0.15\text{ V}$ | | $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$ | | $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ | | $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ | | UNIT |
|-----------|-----------------|----------------|---|-----|--|-----|--|-----|--|-----|------|
| | | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| t_{pd} | A | Y | 1.8 | 7.2 | 1 | 3.9 | 1 | 3.4 | 1 | 2.9 | ns |

Operating Characteristics

$T_A = 25^\circ\text{C}$

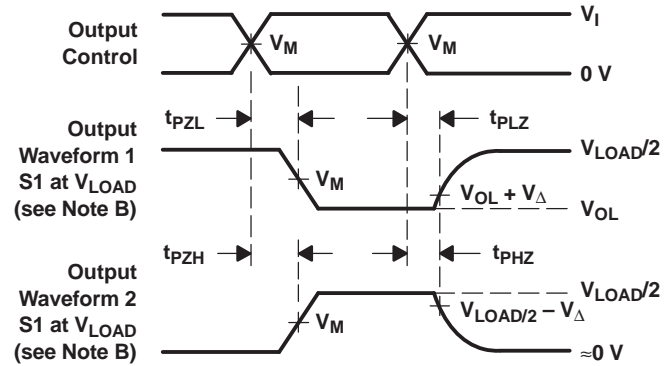
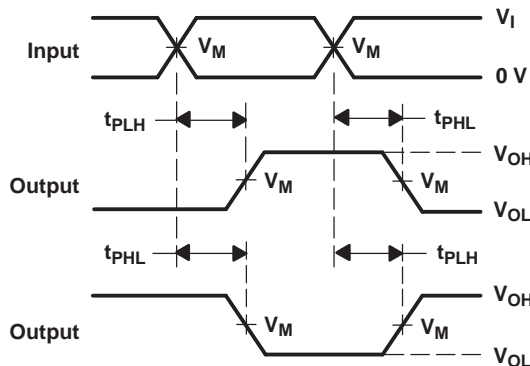
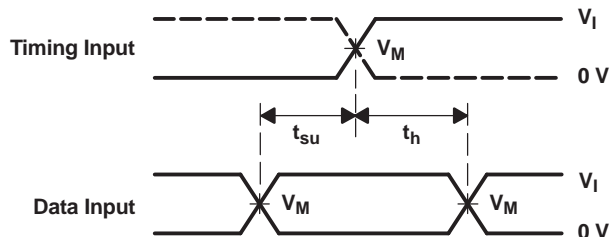
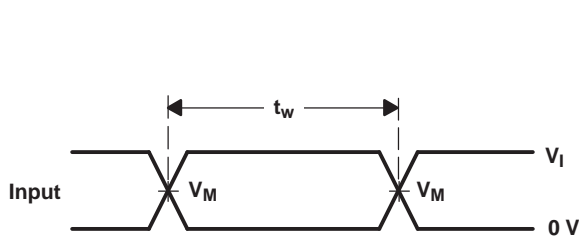
| PARAMETER | TEST CONDITIONS | $V_{CC} = 1.8\text{ V}$ | $V_{CC} = 2.5\text{ V}$ | $V_{CC} = 3.3\text{ V}$ | $V_{CC} = 5\text{ V}$ | UNIT |
|--|---------------------|-------------------------|-------------------------|-------------------------|-----------------------|------|
| | | TYP | TYP | TYP | TYP | |
| C_{pd} Power dissipation capacitance | $f = 10\text{ MHz}$ | 2 | 2 | 3 | 4 | pF |

PARAMETER MEASUREMENT INFORMATION (OPEN DRAIN)



| TEST | S1 |
|-------------------------------|------------|
| t_{PZL} (see Notes E and F) | V_{LOAD} |
| t_{PLZ} (see Notes E and G) | V_{LOAD} |
| t_{PHZ}/t_{PZH} | V_{LOAD} |

| V_{CC} | INPUT | | V_M | V_{LOAD} | C_L | R_L | V_{Δ} |
|--------------------|----------|---------------|------------|-------------------|-------|--------------|--------------|
| | V_I | t_r/t_f | | | | | |
| $1.8 V \pm 0.15 V$ | V_{CC} | $\leq 2 ns$ | $V_{CC}/2$ | $2 \times V_{CC}$ | 30 pF | 1 k Ω | 0.15 V |
| $2.5 V \pm 0.2 V$ | V_{CC} | $\leq 2 ns$ | $V_{CC}/2$ | $2 \times V_{CC}$ | 30 pF | 500 Ω | 0.15 V |
| $3.3 V \pm 0.3 V$ | 3 V | $\leq 2.5 ns$ | 1.5 V | 6 V | 50 pF | 500 Ω | 0.3 V |
| $5 V \pm 0.5 V$ | V_{CC} | $\leq 2.5 ns$ | $V_{CC}/2$ | $2 \times V_{CC}$ | 50 pF | 500 Ω | 0.3 V |



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, $Z_O = 50 \Omega$.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. Since this device has open-drain outputs, t_{PLZ} and t_{PZL} are the same as t_{pd} .
 - F. t_{PZL} is measured at V_M .
 - G. t_{PLZ} is measured at $V_{OL} + V_{\Delta}$.
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|--------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------|----------------|
| SN74LVC2G06QDCKRQ1 | ACTIVE | SC70 | DCK | 6 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | CTO | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN74LVC2G06-Q1 :

- Catalog: [SN74LVC2G06](#)
- Enhanced Product: [SN74LVC2G06-EP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74LVC2G06QDCKRQ1 | SC70 | DCK | 6 | 3000 | 179.0 | 8.4 | 2.2 | 2.5 | 1.2 | 4.0 | 8.0 | Q3 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74LVC2G06QDCKRQ1 | SC70 | DCK | 6 | 3000 | 203.0 | 203.0 | 35.0 |

DCK (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-203 variation AB.

DCK (R-PDSO-G6)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

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